

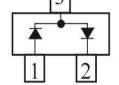
LBAV199LT1G S-LBAV199LT1G

Surface Mount Low Leakage Diode

3 1 2 SOT23(TO-236)

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Ultra-Small Surface Mount Package
- Low Leakage Current



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping		
LBAV199LT1G	52	3000/Tape&Reel		
LBAV199LT3G	52	10000/Tape&Reel		

3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Peak Repetitive Reverse Voltage	VRRM		
Working Peak Reverse Voltage	VRWM	85	V
DC Blocking Voltage	VR		
RMS Reverse Voltage	VR(RMS)	60	V
Forward Continuous Current (Note 1) Single Diode	IFM	215	mA
Double Diode	ILIAI	125	
Repetitive Peak Forward Current	IFRM	500	mΑ
Non-Repetitive Peak Forward Current			Α
t=1µs	IFSM	4	
t=1ms	IFSIVI	1	
t=1s		0.5	
Power Dissipation (Note 1)	PD	150	mW
Thermal Resistance Junction to Ambient Air (Note 1)	RθJA	833	°C/W
Operating and Storage Temperature Range	TJ/Tstg	-65~+150	$^{\circ}$

^{1.}Device mounted on FR-4 PC board with recommended pad layout





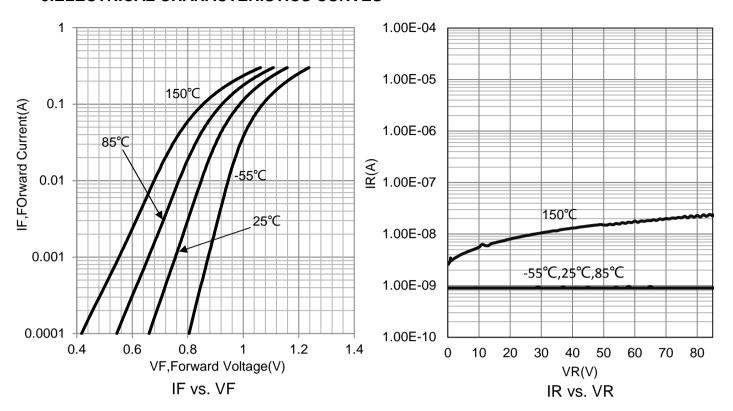
4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

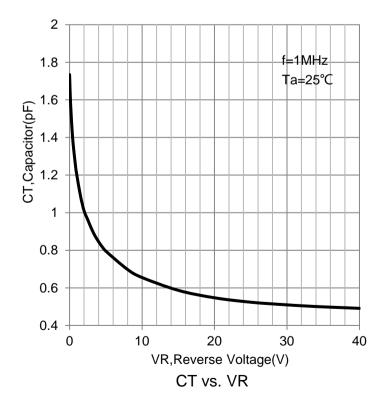
Characteristic	Symbol	Min.	Тур.	Max.	Unit	
Static						
Reverse Breakdown Voltage	\//BD\D				V	
$(IR = 100\mu A)$	V(BR)R	85	-	-	V	
Forward Voltage						
(IF = 1mA)		-	-	0.9		
(IF = 10mA)	VF	-	-	1	V	
(IF = 50mA)		-	-	1.1		
(IF = 150mA)		-	-	1.25		
Leakage Current (Note 2)						
(VR=75V)	IR	-	-	5	nA	
(VR=75V,Tj=150℃)		-	-	80		
Total Capacitance	СТ				ηE	
(VR=0,f=1MHz)	Ci	-	2	-	pF	
Reverse Recovery Time	trr				110	
(IF = IR = $10mA$,Irr = $0.1 \times IR$, RL = 100Ω)	L(1)	-	-	3	μs	

^{2.} Short duration test pulse used to minimize self-heating effect.



5.ELECTRICAL CHARACTERISTICS CURVES







6.OUTLINE AND DIMENSIONS

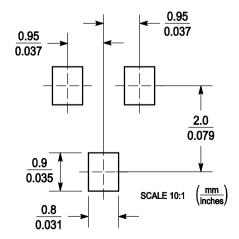
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Notes:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
Е	1.20	1.3	1.4	0.047	0.051	0.055
е	1.78	1.9	2.04	0.07	0.075	0.081
Г	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H _E	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°		10°	0°		10°

7.SOLDERING FOOTPRINT





DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee. The curve of test items without electric parameter is used as reference only.
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